WHAT IS CLAIMED IS:

1. A plating method comprising oxidizing first metal ions of a redox system of a plating bath from a lower oxidation state to a higher oxidation state, and second metal ions of said redox system are reduced and deposited onto the surface of an object to be plated, wherein a process is provided in which by supplying an electrical current to the plating bath, the first metal ions are reduced from said higher oxidation state to said lower oxidation state to thereby activate the plating bath.

2. A plating method as in Claim 1, wherein the process for activating the plating bath by supplying the bath with current is carried out prior to performing said plating method comprising reduction and deposition of the second metal ions.

3. A plating method as in Claim 2, wherein the process for activating the plating bath by supplying the bath with current is carried out in a preparation tank which is divided into a cathode chamber and an anode chamber by means of a partition film.

4. A plating method as in Claim 1, wherein the process for activating the plating bath by supplying the bath with current is carried out simultaneous with the plating method comprising reduction and deposition of the second metal ions.

5. A plating method as in Claim 4, wherein the process for activating the plating bath by supplying the bath with electrical current is carried out in a preparation tank, and the activated plating bath is intermittently or

continuously supplied to a plating tank.

6. A plating method as in Claim 5, wherein the process for activating the plating bath by supplying the bath with current is carried out in a preparation tank which is divided into a cathode chamber and an anode chamber by means of a partition film.

7. A plating method as in Claim 1, wherein the activation process is carried out by using as a cathode an electrode formed from the same metal as the second metal ions.

8. A plating method as in Claim 1, wherein the process for activating the plating bath by supplying the bath with current is carried out in a preparation tank which is divided into a cathode chamber containing a cathode electrode and anode chamber containing an anode electrode by an ion exchange membrane utilized as a partition film while supplying a plating bath to be activated only to the cathode chamber and withdrawing the activated bath only from the cathode chamber, wherein at least said cathode electrode is a carbon electrode.

9. A plating method as in Claim 8, wherein said carbon electrode comprises a porous carbon having a specific surface area of at least $1m^2/g$.

10. A plating method as in Claim 8, wherein the surface of said carbon electrode is oxidized.

11. A plating method as in Claim 10, wherein said carbon electrode is formed by anodic oxidation processing in an electrolyte solution.

12. A plating method as in Claim 8, wherein said activation of the plating

bath is carried out in the cathode chamber while supplying dilute sulfuric acid to the anode chamber as an anode liquid.

13. A plating method as in Claim 8, wherein a metal or a compound thereof which can act as a source of the second metal ions is added to the activated plating bath before use.

14. A plating bath precursor comprising first and second metal ions forming a redox system, said plating bath precursor being stabilized against reduction and deposition of the second metal ions.

15. A plating bath precursor as in Claim 14, wherein the second metal ions are one or more metal ions selected from nickel, cobalt, gold, silver, copper, palladium, platinum, indium, tin, lead, antimony, cadmium, zinc, and iron ions, and the first metal ions are one or more ions selected from titanium, cobalt, tin, vanadium, iron, and chromium ions, which second ions form a redox system in combination with said first metal ions and reduce and deposit the second metal ions.

16. A plating bath precursor as in Claim 15, wherein the concentration of ions of said first metal in a higher oxidation state composing the redox system is at least 0.001 mole/liter.